



# Product Change Notification

## 112432 - 00

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# Product Change Notification

**Change Notification #:** 112432 - 00  
**Change Title:** Intel® NUC Kit DCCP847DY, Boxed  
PCN 112432-00  
Product Design and Documentation,  
Change Bottom Cover, Update Attention  
Flyer and Integration Guide  
**Date of Publication:** July 11, 2013

## Key Characteristics of the Change:

Product Design  
Documentation

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Aug 01, 2013
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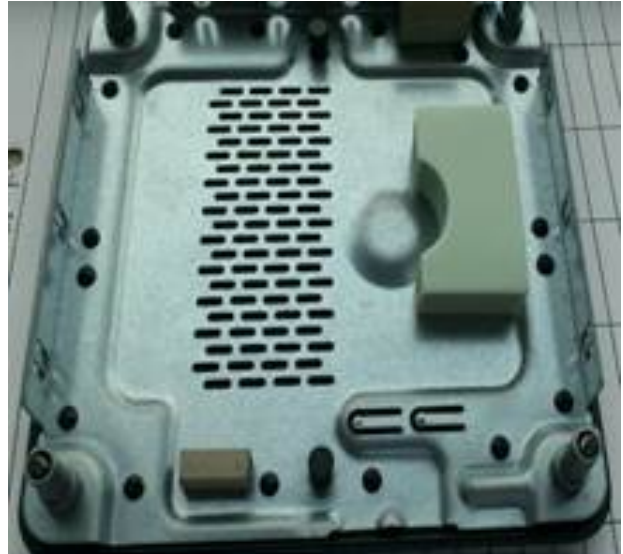
## Description of Change to the Customer:

Intel will be upgrading the bottom cover to include a 9.5mm thermal pad to enhance the thermal design.

Current Bottom Cover:



New Bottom Cover:



Also, the attention flyer and the integration guide for Intel® NUC Kit DCCP847DY will be updated.

**Customer Impact of Change and Recommended Action:**

This change has been thoroughly evaluated to ensure there is no quality, reliability or functional implication to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

**Products Affected / Intel Ordering Codes:**

<b>Product Code</b>	<b>MM#</b>	<b>Pre Change TA</b>	<b>Pre Change SA</b>	<b>Post Change TA</b>	<b>Post Change SA</b>
BOXDCCP847DYE	925743	G79523-104	G80888-103	G79523-105	G80888-104

**PCN Revision History:**

**Date of Revision:**

July 11, 2013

**Revision Number:**

00

**Reason:**

Originally Published PCN